

SNx4HC138 3-Line To 8-Line Decoders/Demultiplexers

1 Features

- Targeted Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Wide Operating Voltage Range (2 V to 6 V)
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- μ A Maximum I_{CC}
- Typical $t_{pd} = 15$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1- μ A Maximum
- Active Low Outputs (Selected Output is Low)
- Incorporate Three Enable Inputs to Simplify Cascading or Data Reception

2 Applications

- LED Displays
- Servers
- White Goods
- Power Infrastructure
- Building Automation
- Factory Automation

3 Description

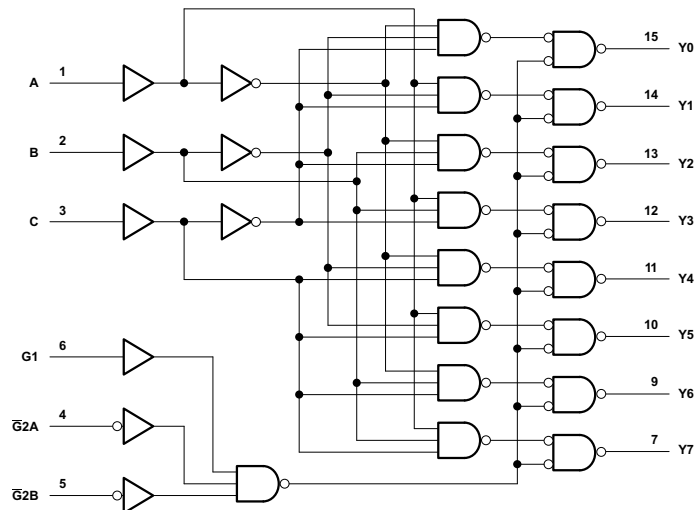
The SNx4HC138 devices are designed to be used in high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories using a fast enable circuit, the delay times of these decoders and the enable time of the memory are usually less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74HC138D	SOIC (16)	9.90 mm x 3.90 mm
SN74HC138DB	SSOP (16)	6.20 mm x 5.30 mm
SN74HC138N	PDIP (16)	19.32 mm x 6.35 mm
SN74HC138NS	SO (16)	10.20 mm x 5.30 mm
SN74HC138PW	TSSOP (16)	5.00 mm x 4.40 mm
SN54HC138J	CDIP (16)	21.34 mm x 6.92 mm
SN54HC138W	CFP (16)	10.16 mm x 6.73 mm
SN54HC138FK	LCCC (20)	8.89 mm x 8.89 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Logic Diagram (Positive Logic)



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Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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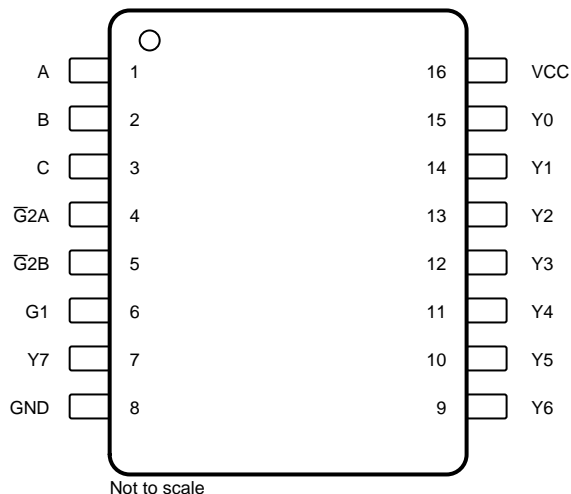
4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

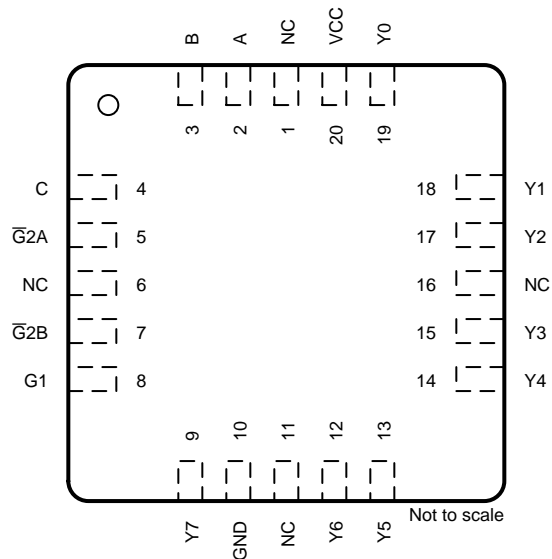
Changes from Revision E (September 2003) to Revision F	Page
• Added <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1
• Deleted Ordering Information table; see POA at the end of the data sheet	1
• Changed $R_{\theta JA}$ values from 73 to 87.3 (D), from 82 to 104.3 (DB), from 67 to 54.8 (N), from 64 to 91.1 (NS), and from 108 to 114.6 (PW)	5

5 Pin Configuration and Functions

SOIC, SSOP, PDIP, SO, TSSOP, CDIP, or CFP Package
16-Pin D, DB, N, NS, PW, J or W
Top View



LCCC Package
20-Pin FK
Top View



NC: No internal connection

Pin Functions

NAME	PIN		I/O	DESCRIPTION
	SOIC, SSOP, PDIP, SO, TSSOP, CDIP, CFP	LCCC		
A	1	2	I	Select input A (least significant bit)
B	2	3	I	Select input B
C	3	4	I	Select input C (most significant bit)
$\overline{G}2A$	4	5	I	Active low enable A
$\overline{G}2B$	5	7	I	Active low enable B
G1	6	8	I	Active high enable
GND	8	10	—	Ground
NC	—	1, 6, 11, 16	—	No internal connection
V_{CC}	16	20	—	Supply voltage
Y0	15	19	O	Output 0 (least significant bit)
Y1	14	18	O	Output 1
Y2	13	17	O	Output 2
Y3	12	15	O	Output 3
Y4	11	14	O	Output 4
Y5	10	13	O	Output 5
Y6	9	12	O	Output 6
Y7	7	9	O	Output 7 (most significant bit)

6 Specifications

6.1 Absolute Maximum Ratings

 over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Supply voltage range, V_{CC}		-0.5	7	V
Input clamp current, $I_{IK}^{(2)}$	$V_I < 0$ or $V_I > V_{CC}$		± 20	mA
Output clamp current, $I_{OK}^{(2)}$	$V_O < 0$ or $V_O > V_{CC}$		± 20	mA
Continuous output current, I_O	$V_O = 0$ to V_{CC}		± 25	mA
Continuous current through V_{CC} or GND			± 50	mA
Junction temperature, T_J			150	°C
Storage temperature, T_{stg}		-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings: SN74HC138

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	± 2000	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	± 1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

 over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	NOM	MAX	UNIT
V_{CC} Supply voltage		2	5	6	V
V_{IH} High-level input voltage	$V_{CC} = 2$ V	1.5			V
	$V_{CC} = 4.5$ V	3.15			
	$V_{CC} = 6$ V	4.2			
V_{IL} Low-level input voltage	$V_{CC} = 2$ V			0.5	V
	$V_{CC} = 4.5$ V			1.35	
	$V_{CC} = 6$ V			1.8	
V_I Input voltage		0		V_{CC}	V
V_O Output voltage		0		V_{CC}	V
$\Delta t/\Delta v$ Input transition rise or fall time	$V_{CC} = 2$ V			1000	ns
	$V_{CC} = 4.5$ V			500	
	$V_{CC} = 6$ V			400	
C_{pd} Power dissipation capacitance (no load)			85		pF
T_A Operating free-air temperature	SN54HC138	-55		125	°C
	SN74HC138	-40		85	

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See TI application report, [Implications of Slow or Floating CMOS Inputs](#) (SCBA004).

6.4 Thermal Information: SN74HC138

THERMAL METRIC ⁽¹⁾		SN74HC138					UNIT
		D (SOIC)	DB (SSOP)	N (PDIP)	NS (SO)	PW (TSSOP)	
		16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	87.3	104.3	54.8	91.1	114.6	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	45.8	54.7	42.1	49.5	49.5	°C/W
R _{θJB}	Junction-to-board thermal resistance	44.8	54.9	34.8	51.5	59.6	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	14.2	17.7	27	17.8	6.9	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	44.5	54.4	34.7	51.2	59.1	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Thermal Information: SN54HC138

THERMAL METRIC ⁽¹⁾		SN54HC138 ⁽²⁾			UNIT
		J (CDIP)	W (CFP)	FK (LCCC)	
		16 PINS	16 PINS	20 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	—	—	—	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	45.4	68.1	49	°C/W
R _{θJB}	Junction-to-board thermal resistance	—	118.4	47.7	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	—	—	7.2	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	62.5	—	—	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	17.7	9	—	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

(2) R_{θJC} follows MIL-STD-883, and R_{θJB} follows JESD51.

6.6 Electrical Characteristics

T_A = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	V _{CC} = 2 V	1.9	1.998	V
			V _{CC} = 4.5 V	4.4	4.499	
			V _{CC} = 6 V	5.9	5.999	
		I _{OH} = -4 mA, V _{CC} = 4.5 V	3.98	4.3		
		I _{OH} = -5.2 mA, V _{CC} = 6 V	5.48	5.8		
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	V _{CC} = 2 V	0.002	0.1	V
			V _{CC} = 4.5 V	0.001	0.1	
			V _{CC} = 6 V	0.001	0.1	
		I _{OL} = 4 mA, V _{CC} = 4.5 V	0.17	0.26		
		I _{OL} = 5.2 mA, V _{CC} = 6 V	0.15	0.26		
I _I	V _I = V _{CC} or 0, V _{CC} = 6 V			±0.1	±100	nA
I _{CC}	V _I = V _{CC} or 0, I _O = 0, V _{CC} = 6 V				8	μA
C _i	V _{CC} = 2 V to 6 V			3	10	pF

6.7 Electrical Characteristics: SN74HC138

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -20 \mu A$	$V_{CC} = 2 V$		1.9	V
			$V_{CC} = 4.5 V$		4.4	
			$V_{CC} = 6 V$		5.9	
		$I_{OH} = -4 mA, V_{CC} = 4.5 V$			3.84	
		$I_{OH} = -5.2 mA, V_{CC} = 6 V$		5.34		
V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_{OL} = 20 \mu A$	$V_{CC} = 2 V$		0.1	V
			$V_{CC} = 4.5 V$		0.1	
			$V_{CC} = 6 V$		0.1	
		$I_{OL} = 4 mA, V_{CC} = 4.5 V$			0.33	
		$I_{OL} = 5.2 mA, V_{CC} = 6 V$		0.33		
I_I	$V_I = V_{CC}$ or 0, $V_{CC} = 6 V$				±1000	nA
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0, V_{CC} = 6 V$				80	μA
C_i	$V_{CC} = 2 V$ to 6 V				10	pF

6.8 Electrical Characteristics: SN54HC138

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	MIN	TYP	MAX	UNIT
V_{OH}	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -20 \mu A$	$V_{CC} = 2 V$		1.9	V	
			$V_{CC} = 4.5 V$		4.4		
			$V_{CC} = 6 V$		5.9		
		$I_{OH} = -4 mA, V_{CC} = 4.5 V$			3.7		
		$I_{OH} = -5.2 mA, V_{CC} = 6 V$		5.2			
V_{OL}	$V_I = V_{IH}$ or V_{IL}	$I_{OL} = 20 \mu A$	$V_{CC} = 2 V$		0.1	V	
			$V_{CC} = 4.5 V$		0.1		
			$V_{CC} = 6 V$		0.1		
		$I_{OL} = 4 mA, V_{CC} = 4.5 V$			0.4		
		$I_{OL} = 5.2 mA, V_{CC} = 6 V$		0.4			
I_I	$V_I = V_{CC}$ or 0, $V_{CC} = 6 V$				±1000	nA	
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0, V_{CC} = 6 V$				160	μA	
C_i	$V_{CC} = 2 V$ to 6 V				10	pF	

6.9 Switching Characteristics

 $T_A = 25^\circ C$ and $C_L = 50 pF$ (unless otherwise noted; see [Parameter Measurement Information](#))

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{pd}	From A, B, or C (input) to any Y (output)	$V_{CC} = 2 V$		67	180	ns
		$V_{CC} = 4.5 V$		18	36	
		$V_{CC} = 6 V$		15	31	
	From enable (input) to any Y (output)	$V_{CC} = 2 V$		66	155	
		$V_{CC} = 4.5 V$		18	31	
		$V_{CC} = 6 V$		15	26	
t_t	To any output	$V_{CC} = 2 V$		38	75	ns
		$V_{CC} = 4.5 V$		8	15	
		$V_{CC} = 6 V$		6	13	

6.10 Switching Characteristics: SN74HC138

over recommended operating free-air temperature range and $C_L = 50$ pF (unless otherwise noted; see [Parameter Measurement Information](#))

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{pd}	From A, B, or C (input) to any Y (output)	$V_{CC} = 2$ V		225	ns
		$V_{CC} = 4.5$ V		45	
		$V_{CC} = 6$ V		38	
	From enable (input) to any Y (output)	$V_{CC} = 2$ V		195	
		$V_{CC} = 4.5$ V		39	
		$V_{CC} = 6$ V		33	
t_t	To any output	$V_{CC} = 2$ V		95	ns
		$V_{CC} = 4.5$ V		19	
		$V_{CC} = 6$ V		16	

6.11 Switching Characteristics: SN54HC138

over recommended operating free-air temperature range and $C_L = 50$ pF (unless otherwise noted; see [Parameter Measurement Information](#))

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{pd}	From A, B, or C (input) to any Y (output)	$V_{CC} = 2$ V		270	ns
		$V_{CC} = 4.5$ V		54	
		$V_{CC} = 6$ V		46	
	From enable (input) to any Y (output)	$V_{CC} = 2$ V		235	
		$V_{CC} = 4.5$ V		47	
		$V_{CC} = 6$ V		40	
t_t	To any output	$V_{CC} = 2$ V		110	ns
		$V_{CC} = 4.5$ V		22	
		$V_{CC} = 6$ V		19	

6.12 Typical Characteristic

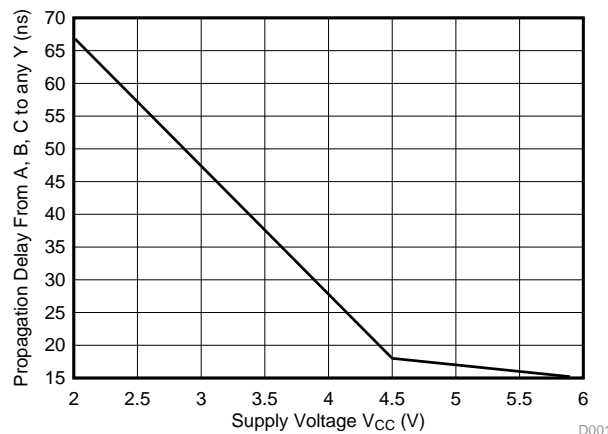
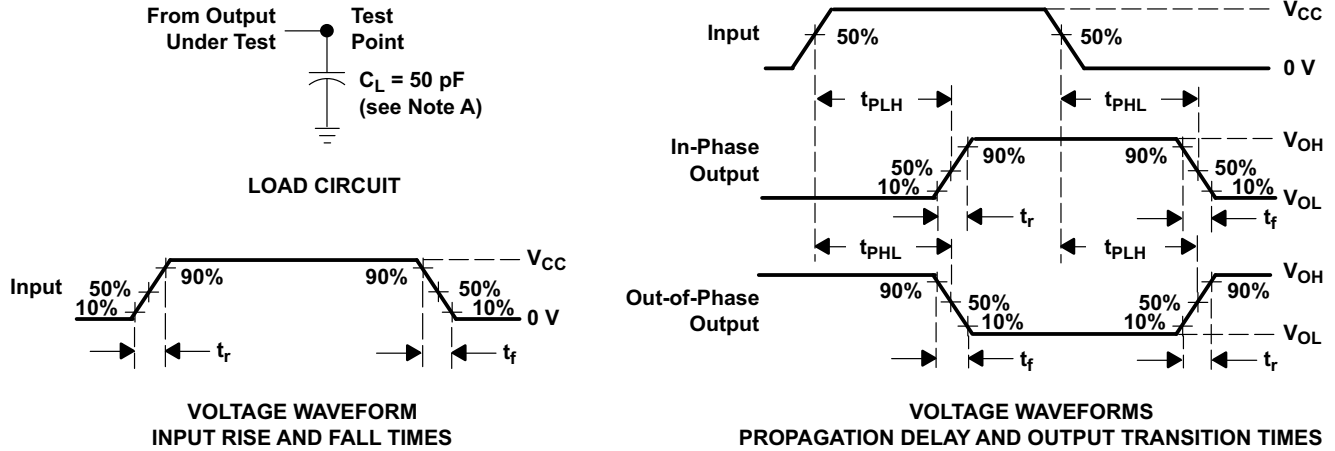


Figure 1. Typical Propagation Delay vs Supply Voltage

7 Parameter Measurement Information



- NOTES:
- C_L includes probe and test-fixture capacitance.
 - Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $\text{PRR} \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 - The outputs are measured one at a time with one input transition per measurement.
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

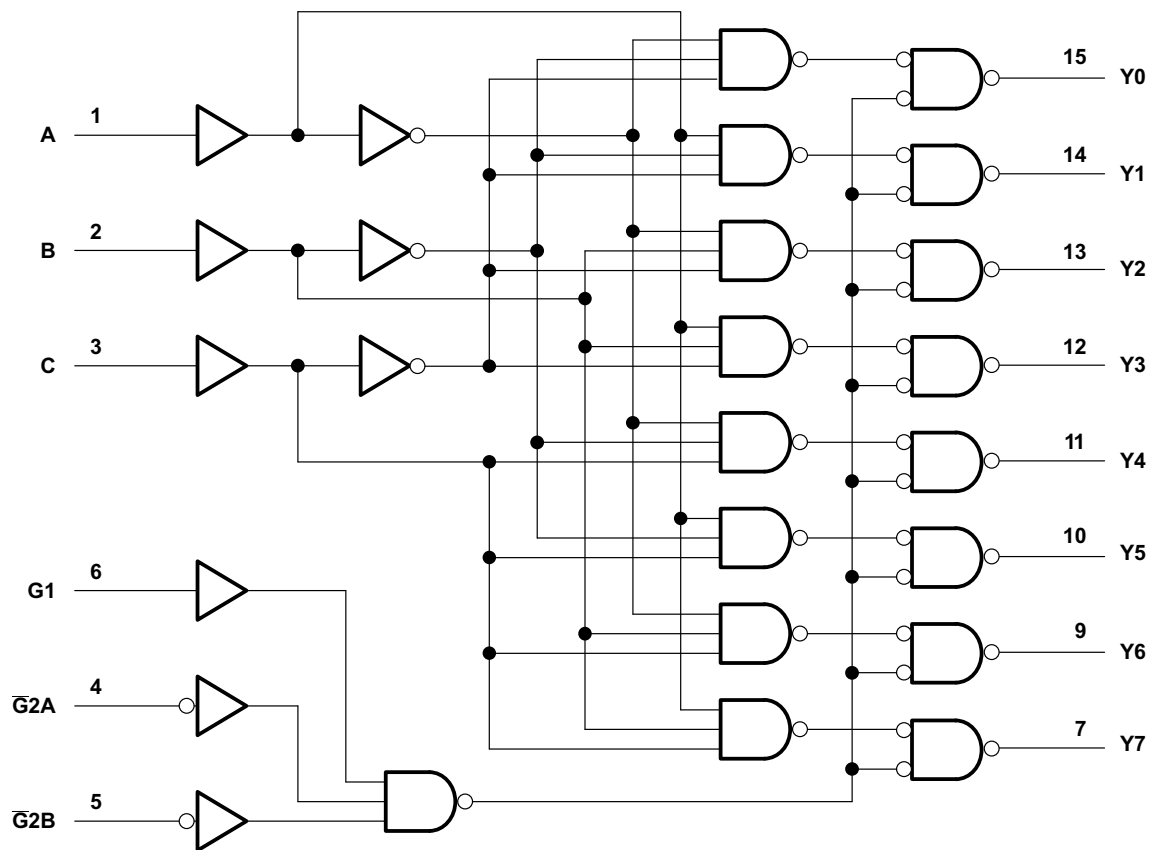
Figure 2. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

The SNx4HC138 devices are 3-to-8 decoders and demultiplexers. The three input pins, A, B, and C, select which output is active. The selected output is pulled LOW, while the remaining outputs are all HIGH. The conditions at the binary-select inputs at the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the requirement for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

8.2 Functional Block Diagram



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Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

Figure 3. Logic Diagram (Positive Logic)

8.3 Feature Description

This device features three binary inputs to select a single active-low output. Three enable pins are also available to enable or disable the outputs. One active high enable and two active low enable pins are available, and any enable pin can be deactivated to force all outputs high. All three enable pins must be active for the output to be enabled.

8.4 Device Functional Modes

Table 1 lists the functions of the SNx4HC138 devices.

Table 1. Function Table

INPUTS						OUTPUTS							
ENABLE			SELECT			Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
G1	$\overline{G2A}$	$\overline{G2B}$	C	B	A								
X	H	X	X	X	X	H	H	H	H	H	H	H	H
X	X	H	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	L	H	H	H	H	H	L	H	H	H	H
H	L	L	H	L	L	H	H	H	H	L	H	H	H
H	L	L	H	L	H	H	H	H	H	H	L	H	H
H	L	L	H	H	L	H	H	H	H	H	H	L	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L

9 Application and Implementation

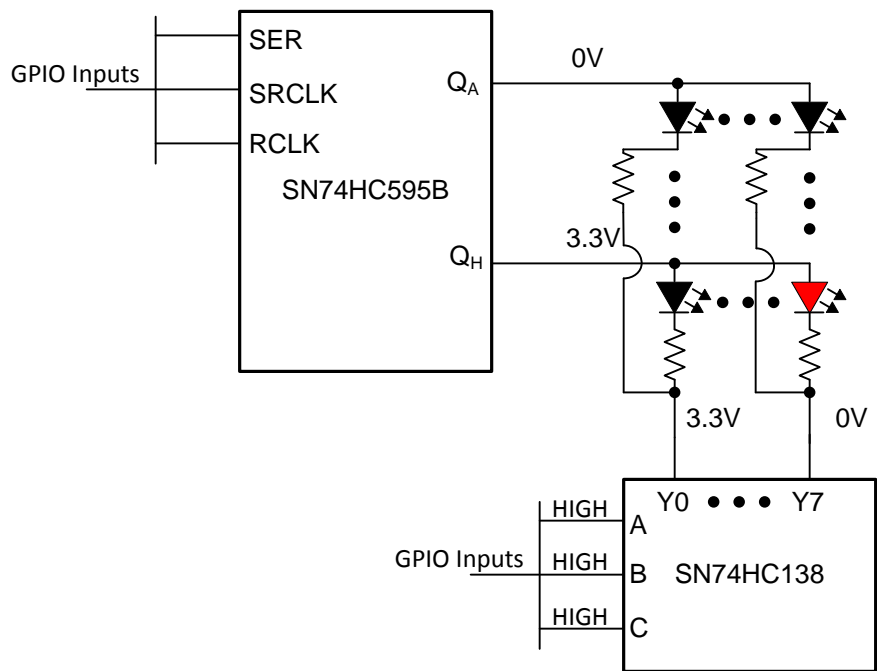
NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The SN74HC138 is useful as a scanning column selector for an LED Matrix display as it can be used for the low side drive of the LED string. The decoder functionality ensures that no more than one output is pulled to a low-level logic voltage so that only a single column is enabled at any point in time.

9.2 Typical Application



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Figure 4. LED Matrix Driver Application

9.2.1 Design Requirements

These devices use CMOS technology and have balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive also creates fast edges into light loads, so routing and load conditions must be considered to prevent ringing.

9.2.2 Detailed Design Procedure

- Recommended Input Conditions
 - For switch time specifications, see propagation delay times in [Switching Characteristics](#).
 - For input voltage level specifications for control inputs, see V_{IH} and V_{IL} in [Electrical Characteristics](#).
- Recommended Output Conditions
 - Outputs must not be pulled above V_{CC} or below GND.

Typical Application (continued)

9.2.3 Application Curve

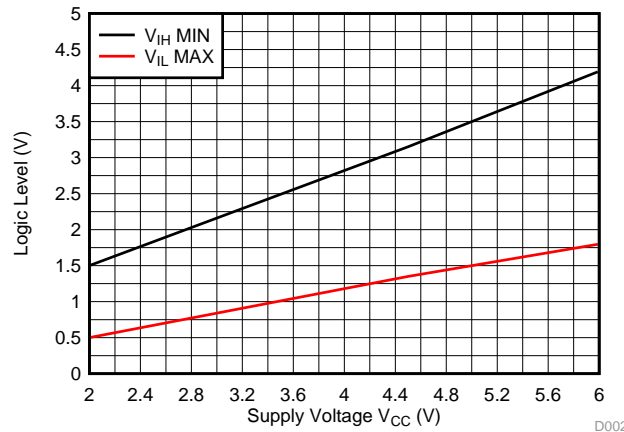


Figure 5. Input High and Input Low Thresholds vs Supply Voltage

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#).

Each V_{CC} terminal must have a good bypass capacitor to prevent power disturbance. A 0.1- μ F bypass capacitor is recommended to be placed close to the V_{CC} terminal. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise; 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor must be installed as close to the power terminal as possible for best results.

11 Layout

11.1 Layout Guidelines

Reflections and matching are closely related to loop antenna theory, but different enough to warrant their own discussion. When a PCB trace turns a corner at a 90° angle, a reflection can occur. This is primarily due to the change of width of the trace. At the apex of the turn, the trace width is increased to 1.414 times its width. This upsets the transmission line characteristics, especially the distributed capacitance and self-inductance of the trace (resulting in the reflection). It is a given that not all PCB traces can be straight, and so they have to turn corners. [Figure 6](#) shows progressively better techniques of rounding corners. Only the last example maintains constant trace width and minimizes reflections.

11.2 Layout Example

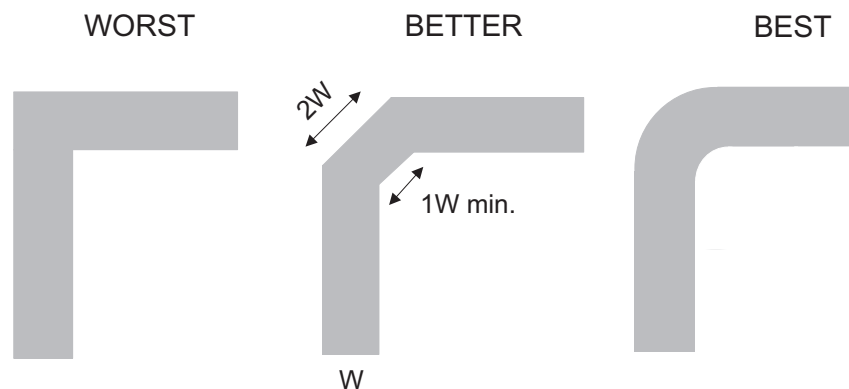


Figure 6. Trace Example

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

[Implications of Slow or Floating CMOS Inputs](#) (SCBA004)

12.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54HC138	Click here	Click here	Click here	Click here	Click here
SN74HC138	Click here	Click here	Click here	Click here	Click here

12.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.5 Trademarks

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All other trademarks are the property of their respective owners.

12.6 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.7 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8406201VEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8406201VE A SNV54HC138J	Samples
5962-8406201VFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8406201VF A SNV54HC138W	Samples
84062012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84062012A SNJ54HC 138FK	Samples
8406201EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8406201EA SNJ54HC138J	Samples
8406201FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8406201FA SNJ54HC138W	Samples
JM38510/65802B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 65802B2A	Samples
JM38510/65802BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 65802BEA	Samples
M38510/65802B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 65802B2A	Samples
M38510/65802BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 65802BEA	Samples
SN54HC138J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC138J	Samples
SN74HC138D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC138DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU CU SN	N / A for Pkg Type	-40 to 85	SN74HC138N	Samples
SN74HC138NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC138N	Samples
SN74HC138NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SN74HC138PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC138	Samples
SNJ54HC138FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84062012A SNJ54HC 138FK	Samples
SNJ54HC138J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8406201EA SNJ54HC138J	Samples
SNJ54HC138W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8406201FA SNJ54HC138W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC138, SN54HC138-SP, SN74HC138 :

● Catalog: [SN74HC138](#), [SN54HC138](#)

● Automotive: [SN74HC138-Q1](#), [SN74HC138-Q1](#)

● Military: [SN54HC138](#)

● Space: [SN54HC138-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC138DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74HC138DR	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC138DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC138DRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC138PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC138PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC138PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC138PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC138DBR	SSOP	DB	16	2000	367.0	367.0	38.0
SN74HC138DR	SOIC	D	16	2500	364.0	364.0	27.0
SN74HC138DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC138DRG4	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC138PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74HC138PWR	TSSOP	PW	16	2000	364.0	364.0	27.0
SN74HC138PWRG4	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74HC138PWT	TSSOP	PW	16	250	367.0	367.0	35.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211284-3/G 08/15

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

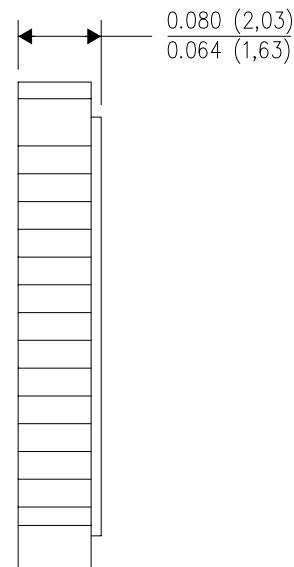
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211283-4/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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